

TSMC-01-413C



April 15, 2004

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/810,965 03/26/04

Yen-Ming Chen et al.

NOVEL METHOD TO IMPROVE BUMP  
RELIABILITY FOR FLIP CHIP DEVICE

#### INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
mail in an envelope addressed to: Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450, on April 26, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

Stephen B. Ackerman 4/26/04

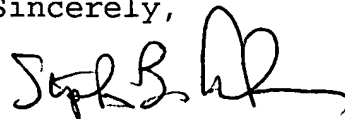
U.S. Patent 5,543,253 to Park et al., "Photomask for T-Gate Formation and Process for Fabricating the Same," discusses a dual damascene like Photo process for a T-gate.

U.S. Patent 6,042,996 to Lin et al., "Method of Fabricating a Dual Damascene Structure," discusses a dual damascene process.

The following four U.S. Patents disclose Bump and UBM processes:

- 1) U.S. Patent 6,232,212 to Degani et al., "Flip Chip Bump Bonding."
- 2) U.S. Patent 6,153,503 to Lin et al., "Continuous Process for Producing Solder Bumps on Electrodes of Semiconductor Chips."
- 3) U.S. Patent 6,130,141 to Degani et al., "Flip Chip Metallization."
- 4) U.S. Patent 6,118,180 to Loo et al., "Semiconductor Die Metal Layout for Flip Chip Packaging."

Sincerely,



Stephen B. Ackerman,  
Reg. No. 37761

# INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

Docket Number (Optional)

TSMC-01-413C

Application Number

10/810,965

Applicant

Yen-Ming Chen et al.

Filing Date

03/26/04

Drawn At Unit

APR 29 2004

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	PENDING DATE IF APPROPRIATE
	5543253	8/6/96	Park et al.	439	5	12/16/94
	6042996	3/28/00	Lin et al.	430	313	4/13/98
	6232212	5/15/01	Degani et al.	438	612	2/23/99
	6153503	11/28/00	Lin et al.	438	613	3/10/98
	6130141	10/10/00	Degani et al.	438	455	10/14/98
	6118180	9/12/00	Lee et al.	257	737	11/3/97

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

## OTHER DOCUMENTS (Including Author, Title, Date, Portmox Pages, Etc.)


EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.